



BUK6Y24-40P

40 V, P-channel Trench MOSFET

8 October 2025

Product data sheet

1. General description

P-channel enhancement mode MOSFET in an LFPAK56 (Power SO8) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

This product has been designed and qualified to AEC-Q101 standard for use in high-performance automotive applications such as reverse battery protection.

2. Features and benefits

- High thermal power dissipation capability
- Suitable for thermally demanding environments due to 175 °C rating
- Trench MOSFET technology
- AEC-Q101 qualified

3. Applications

- Reverse battery protection
- Power management
- High-side load switch
- Motor drive

4. Quick reference data

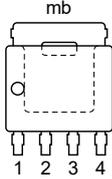
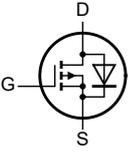
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25\text{ °C}$	-	-	-40	V
V_{GS}	gate-source voltage	[1]	-20	-	20	V
I_D	drain current	$V_{GS} = -10\text{ V}; T_{mb} = 25\text{ °C}$	-	-	-39	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$	-	-	66	W
Static characteristics						
R_{DSon}	drain-source on-state resistance	$V_{GS} = -10\text{ V}; I_D = -8.2\text{ A}; T_j = 25\text{ °C}$	-	19	24	mΩ

[1] $V_{GS} = -20\text{ V}/+5\text{ V}$ according AEC-Q101 at $T_j = 175\text{ °C}$; $V_{GS} = -20\text{ V}/+20\text{ V}$ according AEC-Q101 at $T_j = 150\text{ °C}$

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 <p>LFPAK56; Power-SO8 (SOT669)</p>	 <p>017aaa094</p>
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK6Y24-40P	LFPAK56; Power-SO8	plastic, single-ended surface-mounted package; 4 terminals	SOT669

7. Marking

Table 4. Marking codes

Type number	Marking code
BUK6Y24-40P	6Y2440P

8. Limiting values

Table 5. Limiting values

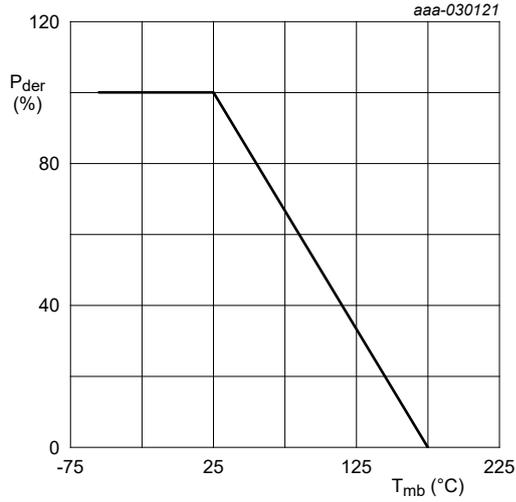
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25\text{ }^\circ\text{C}$		-	-40	V
V_{GS}	gate-source voltage		[1]	-20	20	V
I_D	drain current	$V_{GS} = -10\text{ V}; T_{mb} = 25\text{ }^\circ\text{C}$		-	-39	A
		$V_{GS} = -10\text{ V}; T_{mb} = 100\text{ }^\circ\text{C}$		-	-27	A
I_{DM}	peak drain current	single pulse; $t_p \leq 10\text{ }\mu\text{s}; T_{mb} = 25\text{ }^\circ\text{C}$		-	-155	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ }^\circ\text{C}$		-	66	W
T_j	junction temperature			-55	175	$^\circ\text{C}$
T_{amb}	ambient temperature			-55	175	$^\circ\text{C}$
T_{stg}	storage temperature			-65	175	$^\circ\text{C}$
Source-drain diode						
I_S	source current	$T_{mb} = 25\text{ }^\circ\text{C}$		-	-39	A
I_{SM}	peak source current	single pulse; $t_p \leq 10\text{ }\mu\text{s}; T_{mb} = 25\text{ }^\circ\text{C}$		-	-155	A
ESD maximum rating						
V_{ESD}	electrostatic discharge voltage	HBM	[2]	-	500	V
Avalanche ruggedness						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$V_{sup} \leq -40\text{ V}; V_{GS} = -10\text{ V}; T_{j(\text{init})} = 25\text{ }^\circ\text{C}; R_{GS} = 50\text{ }\Omega; I_D = -24.8\text{ A}; \text{ unclamped}$	[3]	-	61.5	mJ
		$V_{sup} \leq -40\text{ V}; V_{GS} = -10\text{ V}; T_{j(\text{init})} = 25\text{ }^\circ\text{C}; R_{GS} = 50\text{ }\Omega; I_D = -6\text{ A}$	[3]	-	270	mJ
I_{AS}	non-repetitive avalanche current	$T_{j(\text{init})} = 25\text{ }^\circ\text{C}$	[3]	-	-24.8	A

[1] $V_{GS} = -20\text{ V}/+5\text{ V}$ according AEC-Q101 at $T_j = 175\text{ }^\circ\text{C}$; $V_{GS} = -20\text{ V}/+20\text{ V}$ according AEC-Q101 at $T_j = 150\text{ }^\circ\text{C}$

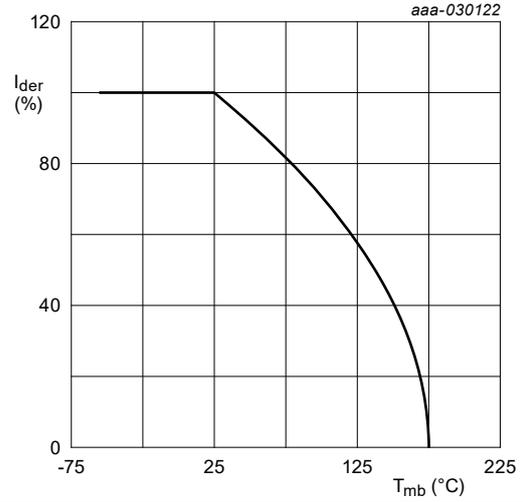
[2] Measured between all pins.

[3] Protected by 100% test.



$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}} \times 100 \%$$

Fig. 1. Normalized total power dissipation as a function of mounting base temperature



$$I_{der} = \frac{I_D}{I_{D(25^{\circ}\text{C})}} \times 100 \%$$

Fig. 2. Normalized continuous drain current as a function of mounting base temperature

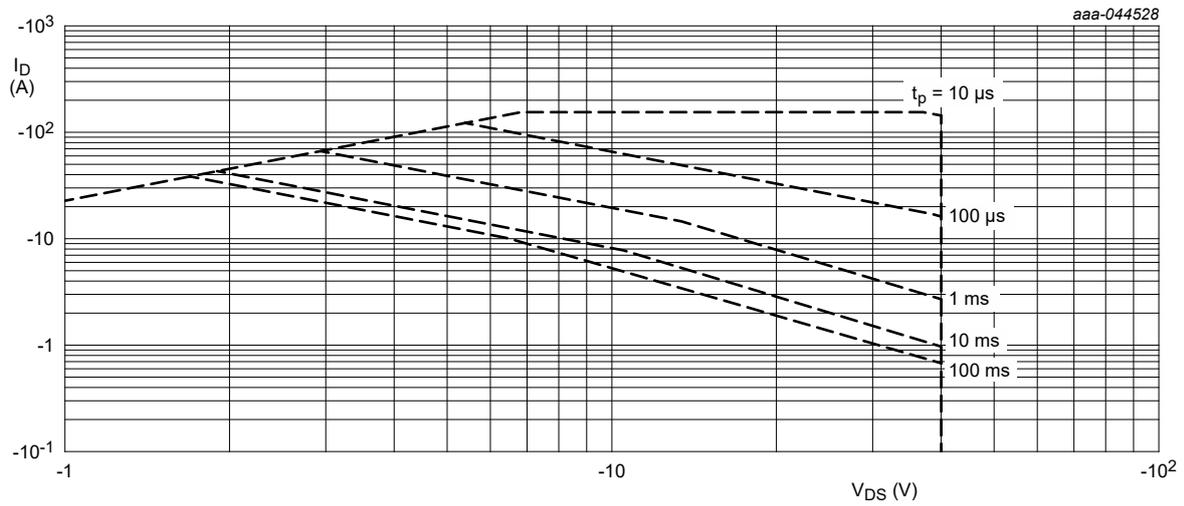


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base		-	1.8	2.3	K/W

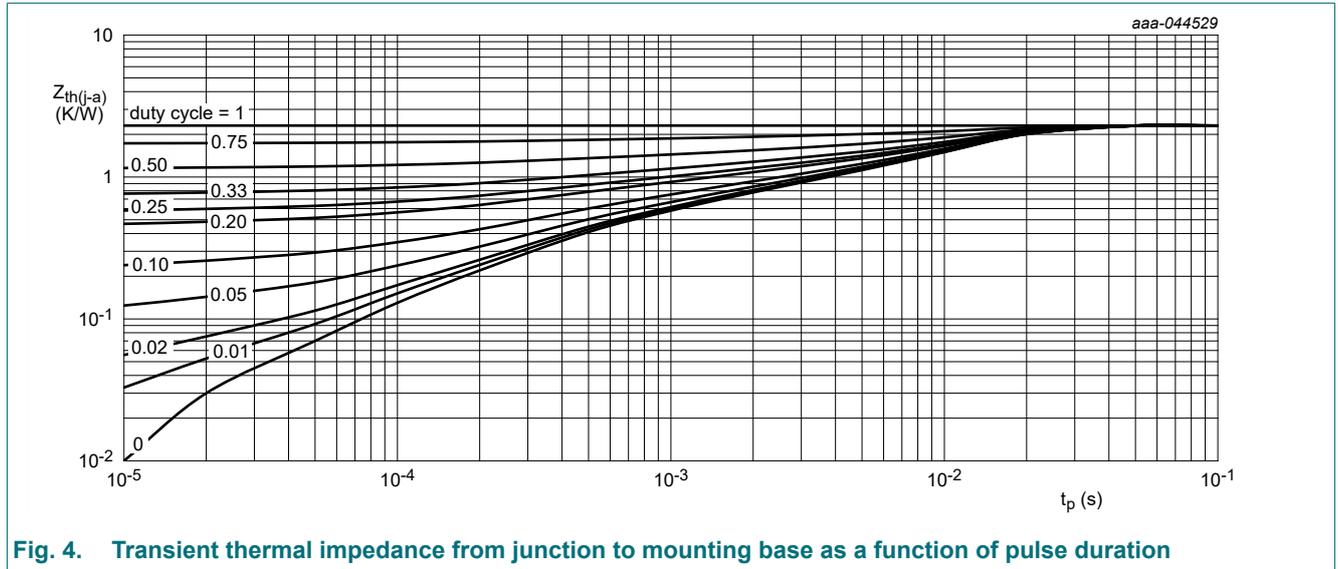


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = -250 \mu\text{A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-40	-	-	V
V_{GSth}	gate-source threshold voltage	$I_D = -250 \mu\text{A}; V_{DS}=V_{GS}; T_j = 25 \text{ }^\circ\text{C}$	-1.5	-2	-3	V
I_{DSS}	drain leakage current	$V_{DS} = -40 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	-	-1	μA
		$V_{DS} = -40 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 125 \text{ }^\circ\text{C}$	-	-	-10	μA
I_{GSS}	gate leakage current	$V_{GS} = -20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	-	-100	nA
		$V_{GS} = 20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	-	100	nA
R_{DSon}	drain-source on-state resistance	$V_{GS} = -10 \text{ V}; I_D = -8.2 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	19	24	m Ω
		$V_{GS} = -10 \text{ V}; I_D = -8.2 \text{ A}; T_j = 175 \text{ }^\circ\text{C}$	-	35	44	m Ω
		$V_{GS} = -4.5 \text{ V}; I_D = -5.6 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	30	50	m Ω
g_{fs}	forward transconductance	$V_{DS} = -10 \text{ V}; I_D = -4 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	14	-	S
R_G	gate resistance	$f = 1 \text{ MHz}$	-	11	-	Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$V_{DS} = -20 \text{ V}; I_D = -8.2 \text{ A}; V_{GS} = -10 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	23	35	nC
Q_{GS}	gate-source charge		-	4	-	nC
Q_{GD}	gate-drain charge		-	5	-	nC
C_{iss}	input capacitance	$V_{DS} = -20 \text{ V}; f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	1250	-	pF
C_{oss}	output capacitance		-	184	-	pF
C_{rss}	reverse transfer capacitance		-	100	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = -20 \text{ V}; I_D = -8.2 \text{ A}; V_{GS} = -10 \text{ V}; R_{G(ext)} = 6 \text{ } \Omega; T_j = 25 \text{ }^\circ\text{C}$	-	4	-	ns
t_r	rise time		-	9	-	ns
$t_{d(off)}$	turn-off delay time		-	42	-	ns
t_f	fall time		-	201	-	ns
Source-drain diode						
V_{SD}	source-drain voltage	$I_S = -6 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	-0.8	-1.2	V
t_{rr}	reverse recovery time	$I_S = -6 \text{ A}; dI_S/dt = 100 \text{ A}/\mu\text{s}; V_{GS} = 0 \text{ V}; V_{DS} = -20 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	18	-	ns
Q_r	recovered charge		-	11	-	nC

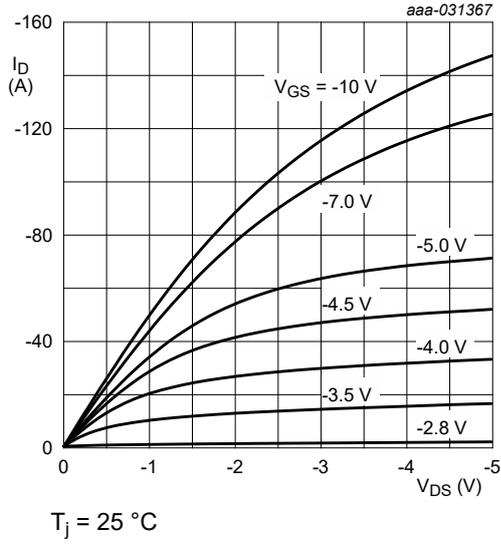


Fig. 5. Output characteristics: drain current as a function of drain-source voltage; typical values

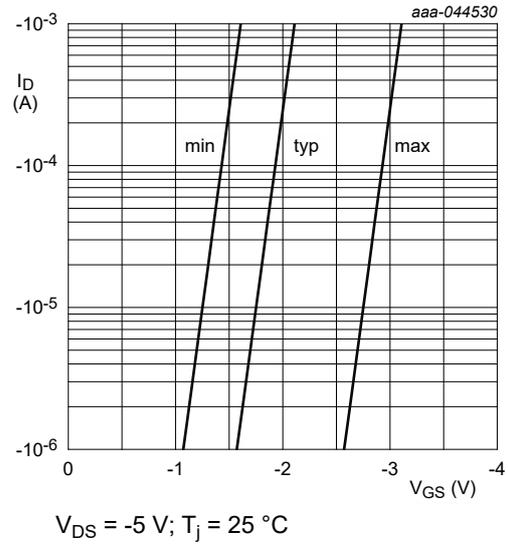


Fig. 6. Sub-threshold drain current as a function of gate-source voltage

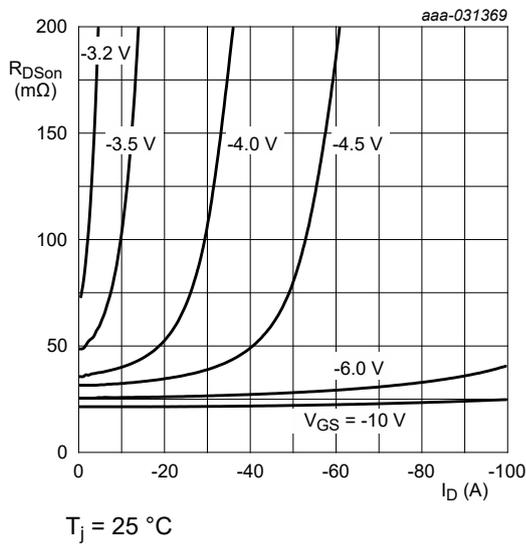


Fig. 7. Drain-source on-state resistance as a function of drain current; typical values

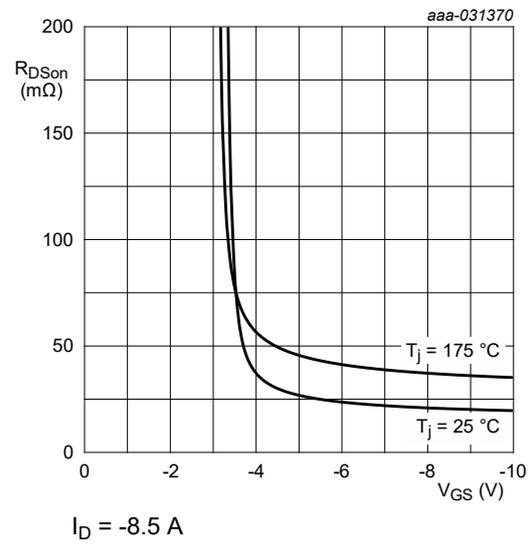


Fig. 8. Drain-source on-state resistance as a function of gate-source voltage; typical values

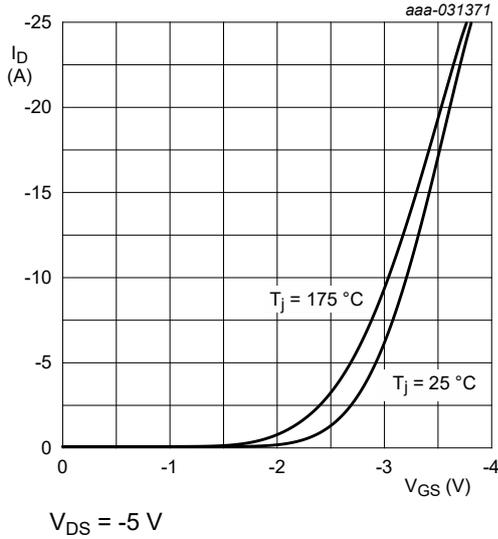


Fig. 9. Transfer characteristics: drain current as a function of gate-source voltage; typical values

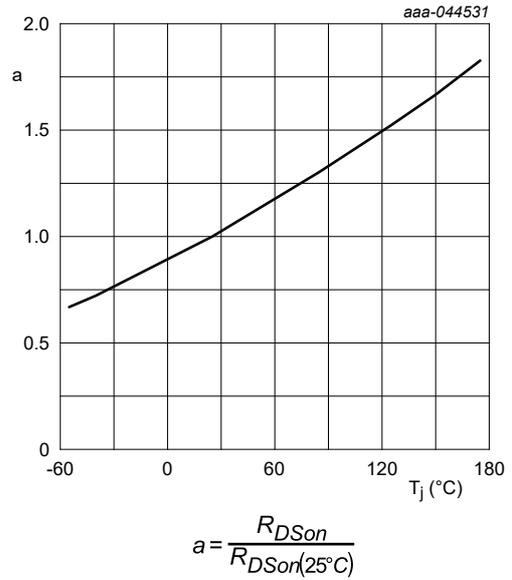


Fig. 10. Normalized drain-source on-state resistance as a function of junction temperature; typical values

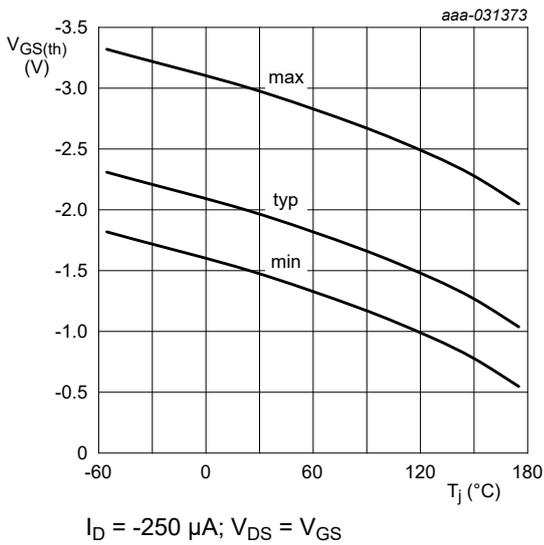


Fig. 11. Gate-source threshold voltage as a function of junction temperature

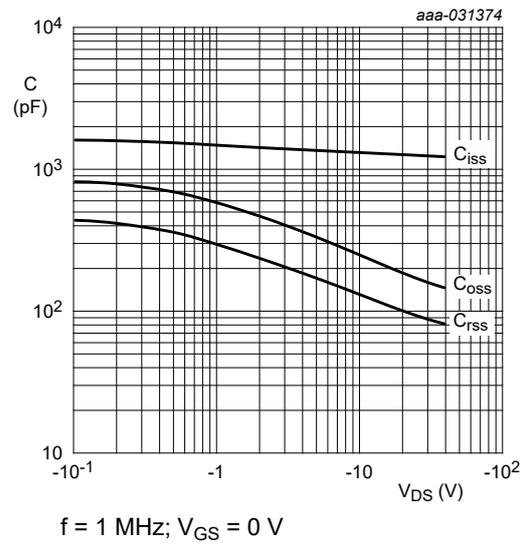
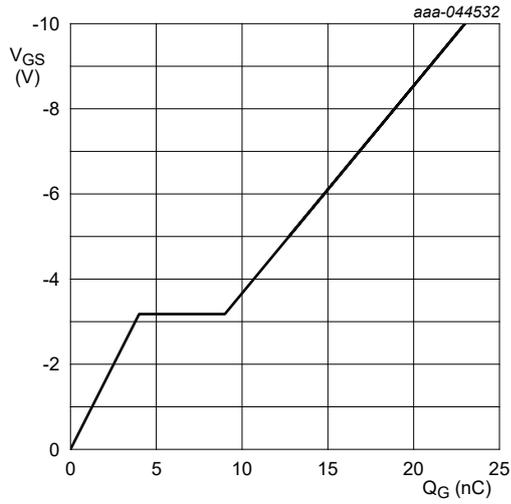


Fig. 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$V_{DS} = -20 \text{ V}; I_D = -8.2 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$

Fig. 13. Gate-source voltage as a function of gate charge; typical values

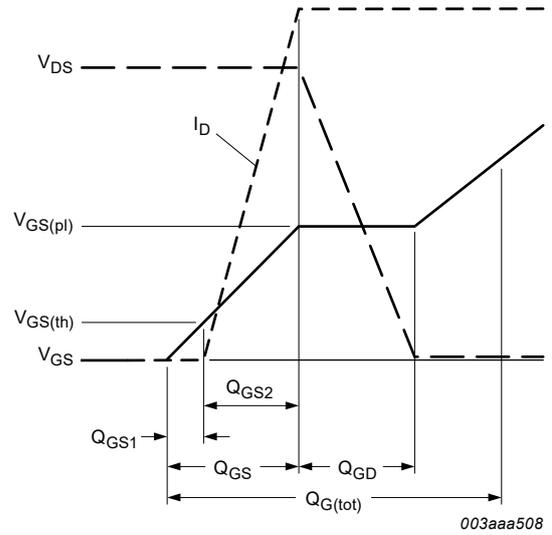
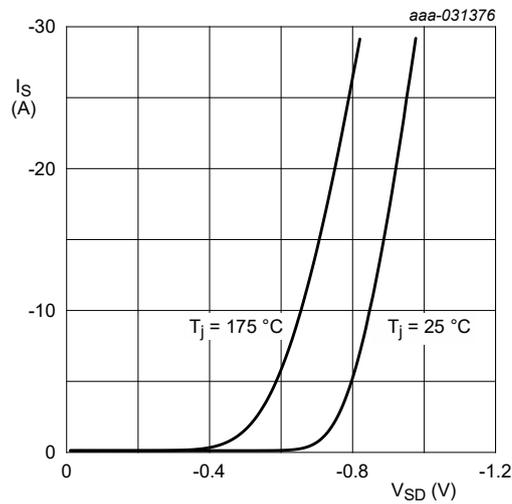


Fig. 14. Gate charge waveform definitions



$V_{GS} = 0 \text{ V}$

Fig. 15. Source current as a function of source-drain voltage; typical values

11. Test information

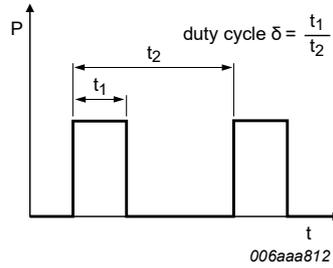


Fig. 16. Duty cycle definition

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

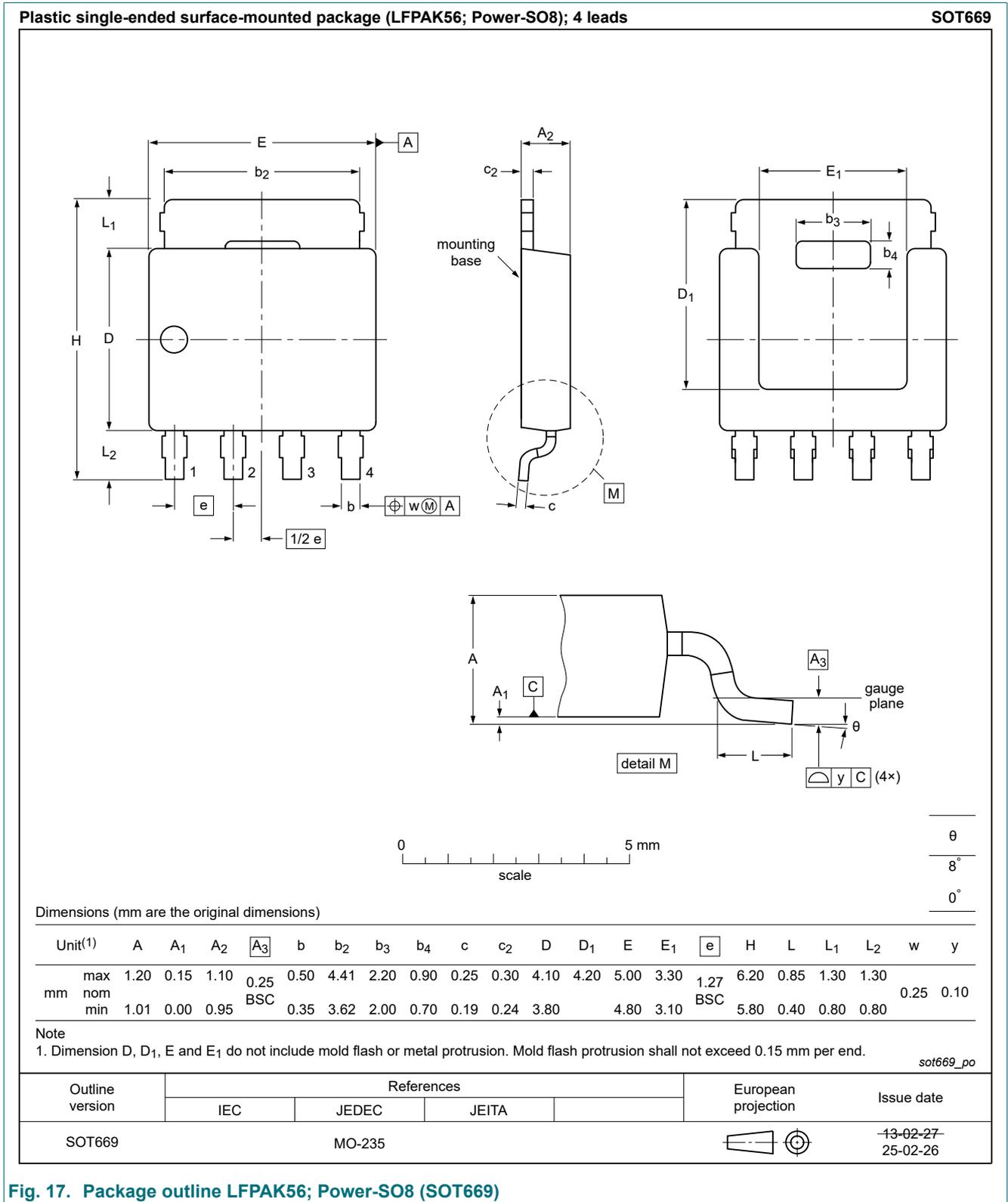


Fig. 17. Package outline LFAK56; Power-SO8 (SOT669)

13. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
BUK6Y24-40P v.2	20251008	Product data sheet	-	BUK6Y24-40P v.1
Modifications:	<ul style="list-style-type: none"> Chapter "Limiting values": added data for avalanche ruggedness. Update of figure 3. Chapter "Thermal characteristics": Update of figure 4. Chapter "Characteristics": Update of table 7 with latest information about dynamic characteristics and source-drain diode. Update of figures 6, 10 and 13. 			
BUK6Y24-40P v.1	20200409	Product data sheet	-	-

14. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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